

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5963594

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
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	Name	Execution Date
	SENLIN LI	02/12/2020
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16790784	
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NAME OF SUBMITTER:	RAYMOND J. CHEW	
SIGNATURE:	/Raymond J. Chew/	
DATE SIGNED:	02/14/2020	
Total Attachments: 2		
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ASSIGNMENT

LI, Senlin having a mailing address 10F Building A3, Innovation Industrial Park, No. 800 West Wangjiang Road, Hefei, Anhui, China, (hereafter referred to as the undersigned), is the inventor of the U.S. patent application to be filed entitled:

COMPOSITE SENSOR AND MANUFACTURING METHOD THEREOF

The above U.S. application was assigned serial no. _____ and was filed on _____. The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

AutoChips Inc. Having a place of business 10F Building A3, Innovation Industrial Park, No. 800 West Wangjiang Road, Hefei, Anhui, China (hereafter referred to as the assignee), is desirous of acquiring the entire right, title and interest in the above-identified application, in said invention described therein, all applications for and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, in any subsequent nonprovisional applications filed for this invention or improvements thereto, and all divisions and continuations thereof, any Registered Community Design applications, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

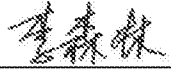
Attorney Docket No.: PAUS1910824

Customer No.: 128477

The undersigned warrant that the rights and property herein conveyed are free and clear of any encumbrance.

Signature of

Inventor 1



Executed Date

2020/2/12

Printed Name Li, Senlin